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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	21225
Number of Logic Elements/Cells	450000
Total RAM Bits	40249344
Number of I/O	534
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agzme7h2f35c3n

Contents

Symbol	Description	Maximum	Unit
$I_{XCVR\text{-}RX\ (DC)}$	DC current per transceiver receiver (RX) pin	50	mA

Internal Weak Pull-Up Resistor

All I/O pins, except configuration, test, and JTAG pins, have an option to enable weak pull-up.

Table 1-13: Internal Weak Pull-Up Resistor Values for Arria V Devices

Symbol	Description	Condition (V)[11]	Value[12]	Unit
R_{PU}	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you have enabled the programmable pull-up resistor option.	V_{CCIO} = 3.3 ±5%	25	kΩ
		V_{CCIO} = 3.0 ±5%	25	kΩ
		V_{CCIO} = 2.5 ±5%	25	kΩ
		V_{CCIO} = 1.8 ±5%	25	kΩ
		V_{CCIO} = 1.5 ±5%	25	kΩ
		V_{CCIO} = 1.35 ±5%	25	kΩ
		V_{CCIO} = 1.25 ±5%	25	kΩ
		V_{CCIO} = 1.2 ±5%	25	kΩ

Related Information

Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines

Provides more information about the pins that support internal weak pull-up and internal weak pull-down features.

(10) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C\ dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

(11) Pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO}.

(12) Valid with ±10% tolerances to cover changes over PVT.

Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications

Table 1-16: Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Arria V Devices

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	V_{OL} (V)	V_{OH} (V)	I_{OL}[14] (mA)	I_{OH}[14] (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	–0.3	V_{REF} – 0.15	V_{REF} + 0.15	V_{CCIO} + 0.3	V_{REF} – 0.31	V_{REF} + 0.31	V_{TT} – 0.608	V_{TT} + 0.608	8.1	–8.1
SSTL-2 Class II	–0.3	V_{REF} – 0.15	V_{REF} + 0.15	V_{CCIO} + 0.3	V_{REF} – 0.31	V_{REF} + 0.31	V_{TT} – 0.81	V_{TT} + 0.81	16.2	–16.2
SSTL-18 Class I	–0.3	V_{REF} – 0.125	V_{REF} + 0.125	V_{CCIO} + 0.3	V_{REF} – 0.25	V_{REF} + 0.25	V_{TT} – 0.603	V_{TT} + 0.603	6.7	–6.7
SSTL-18 Class II	–0.3	V_{REF} – 0.125	V_{REF} + 0.125	V_{CCIO} + 0.3	V_{REF} – 0.25	V_{REF} + 0.25	0.28	V_{CCIO} – 0.28	13.4	–13.4
SSTL-15 Class I	—	V_{REF} – 0.1	V_{REF} + 0.1	—	V_{REF} – 0.175	V_{REF} + 0.175	0.2 × V_{CCIO}	0.8 × V_{CCIO}	8	–8
SSTL-15 Class II	—	V_{REF} – 0.1	V_{REF} + 0.1	—	V_{REF} – 0.175	V_{REF} + 0.175	0.2 × V_{CCIO}	0.8 × V_{CCIO}	16	–16
SSTL-135	—	V_{REF} – 0.09	V_{REF} + 0.09	—	V_{REF} – 0.16	V_{REF} + 0.16	0.2 × V_{CCIO}	0.8 × V_{CCIO}	—	—
SSTL-125	—	V_{REF} – 0.85	V_{REF} + 0.85	—	V_{REF} – 0.15	V_{REF} + 0.15	0.2 × V_{CCIO}	0.8 × V_{CCIO}	—	—
HSTL-18 Class I	—	V_{REF} – 0.1	V_{REF} + 0.1	—	V_{REF} – 0.2	V_{REF} + 0.2	0.4	V_{CCIO} – 0.4	8	–8
HSTL-18 Class II	—	V_{REF} – 0.1	V_{REF} + 0.1	—	V_{REF} – 0.2	V_{REF} + 0.2	0.4	V_{CCIO} – 0.4	16	–16
HSTL-15 Class I	—	V_{REF} – 0.1	V_{REF} + 0.1	—	V_{REF} – 0.2	V_{REF} + 0.2	0.4	V_{CCIO} – 0.4	8	–8

(14) To meet the I_{OL} and I_{OH} specifications, you must set the current strength settings accordingly. For example, to meet the SSTL15CI specification (8 mA), you should set the current strength settings to 8 mA. Setting at lower current strength may not meet the I_{OL} and I_{OH} specifications in the datasheet.

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Spread-spectrum modulating clock frequency	PCI Express® (PCIe)	30	—	33	30	—	33	kHz
Spread-spectrum downspread	PCIe	—	0 to –0.5%	—	—	0 to –0.5%	—	—
On-chip termination resistors	—	—	100	—	—	100	—	Ω
V_{ICM} (AC coupled)	—	—	1.1/1.15[26]	—	—	1.1/1.15[26]	—	V
V_{ICM} (DC coupled)	HCSL I/O standard for the PCIe reference clock	250	—	550	250	—	550	mV
Transmitter REFCLK phase noise[27]	10 Hz	—	—	–50	—	—	–50	dBc/Hz
	100 Hz	—	—	–80	—	—	–80	dBc/Hz
	1 KHz	—	—	–110	—	—	–110	dBc/Hz
	10 KHz	—	—	–120	—	—	–120	dBc/Hz
	100 KHz	—	—	–120	—	—	–120	dBc/Hz
	≥1 MHz	—	—	–130	—	—	–130	dBc/Hz
R_{REF}	—	—	2000 ±1%	—	—	2000 ±1%	—	Ω

(26) For data rate ≤3.2 Gbps, connect $V_{CCR\_GXBL/R}$ to either 1.1-V or 1.15-V power supply. For data rate >3.2 Gbps, connect $V_{CCR\_GXBL/R}$ to a 1.15-V power supply. For details, refer to the Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines.

(27) The transmitter REFCLK phase jitter is 30 ps p-p at bit error rate (BER) 10^{-12}.

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Inter-transceiver block transmitter channel-to-channel skew[39]	×*N* PMA bonded mode	—	—	500	—	—	500	ps

Table 1-24: CMU PLL Specifications for Arria V GX and SX Devices

Symbol/Description	Transceiver Speed Grade 4		Transceiver Speed Grade 6		Unit
	Min	Max	Min	Max	
Supported data range	611	6553.6	611	3125	Mbps
fPLL supported data range	611	3125	611	3125	Mbps

Table 1-25: Transceiver-FPGA Fabric Interface Specifications for Arria V GX and SX Devices

Symbol/Description	Transceiver Speed Grade 4 and 6		Unit
	Min	Max	
Interface speed (single-width mode)	25	187.5	MHz
Interface speed (double-width mode)	25	163.84	MHz

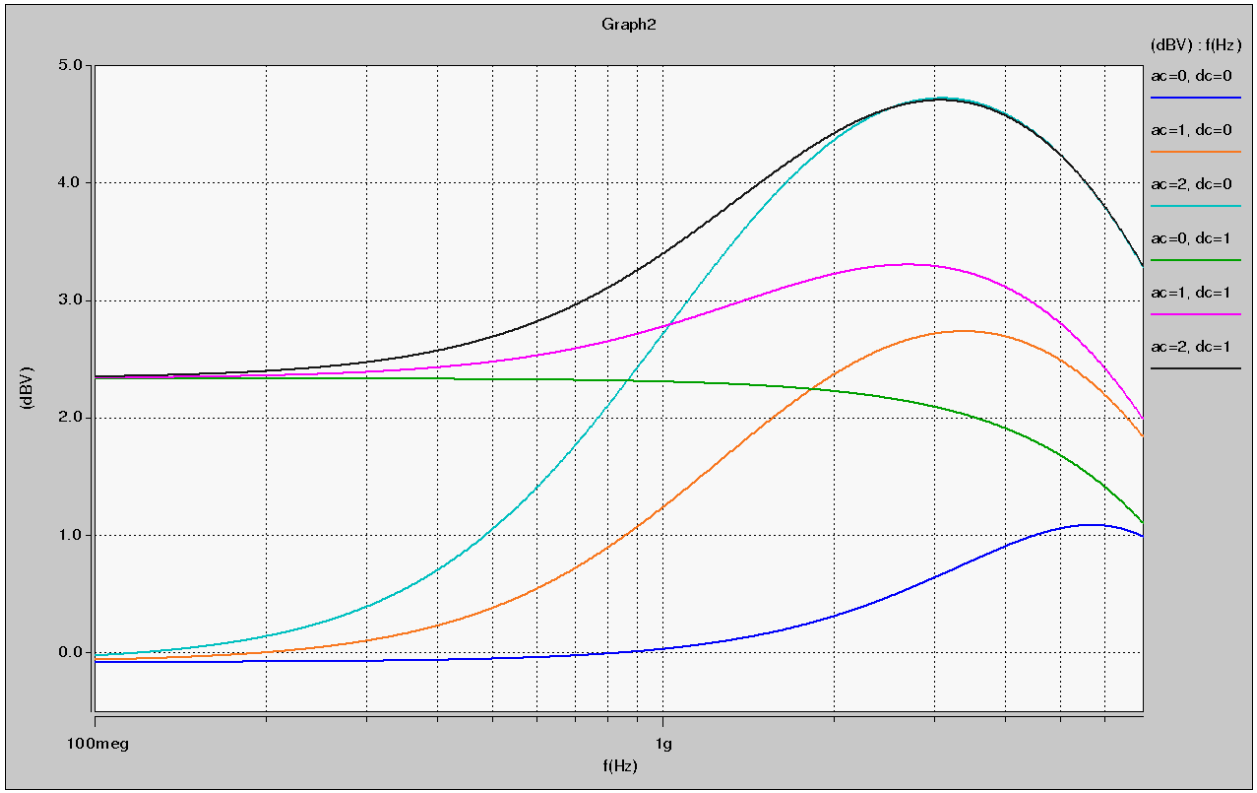
Related Information

- **CTLE Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain** on page 1-35
- **CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain** on page 1-36
- **Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines**
  Provides more information about the power supply connection for different data rates.

[39] This specification is only applicable to channels on one side of the device across two transceiver banks.

CTLE Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain

Figure 1-2: Continuous Time-Linear Equalizer (CTLE) Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain for Arria V GX, GT, SX, and ST Devices



For example, when V_{OD} = 800 mV, the corresponding V_{OD} value setting is 40. The following conditions show that the 1st post tap pre-emphasis setting = 2 is valid:

- $|B| + |C| \leq 60 \rightarrow 40 + 2 = 42$
- $|B| - |C| > 5 \rightarrow 40 - 2 = 38$
- $(V_{MAX}/V_{MIN} - 1)\% < 600\% \rightarrow (42/38 - 1)\% = 10.52\%$

To predict the pre-emphasis level for your specific data rate and pattern, run simulations using the Arria V HSSI HSPICE models.

Table 1-33: Transmitter Pre-Emphasis Levels for Arria V Devices

Quartus Prime 1st Post Tap Pre-Emphasis Setting	Quartus Prime V_{OD} Setting							Unit
	10 (200 mV)	20 (400 mV)	30 (600 mV)	35 (700 mV)	40 (800 mV)	45 (900 mV)	50 (1000 mV)	
0	0	0	0	0	0	0	0	dB
1	1.97	0.88	0.43	0.32	0.24	0.19	0.13	dB
2	3.58	1.67	0.95	0.76	0.61	0.5	0.41	dB
3	5.35	2.48	1.49	1.2	1	0.83	0.69	dB
4	7.27	3.31	2	1.63	1.36	1.14	0.96	dB
5	—	4.19	2.55	2.1	1.76	1.49	1.26	dB
6	—	5.08	3.11	2.56	2.17	1.83	1.56	dB
7	—	5.99	3.71	3.06	2.58	2.18	1.87	dB
8	—	6.92	4.22	3.47	2.93	2.48	2.11	dB
9	—	7.92	4.86	4	3.38	2.87	2.46	dB
10	—	9.04	5.46	4.51	3.79	3.23	2.77	dB
11	—	10.2	6.09	5.01	4.23	3.61	—	dB
12	—	11.56	6.74	5.51	4.68	3.97	—	dB
13	—	12.9	7.44	6.1	5.12	4.36	—	dB
14	—	14.44	8.12	6.64	5.57	4.76	—	dB
15	—	—	8.87	7.21	6.06	5.14	—	dB

Symbol	Parameter	Condition	Min	Typ	Max	Unit
f_{OUT_EXT}	Output frequency for external clock output	–3 speed grade	—	—	670[63]	MHz
		–4 speed grade	—	—	670[63]	MHz
		–5 speed grade	—	—	622[63]	MHz
		–6 speed grade	—	—	500[63]	MHz
$t_{OUTDUTY}$	Duty cycle for external clock output (when set to 50%)	—	45	50	55	%
t_{FCOMP}	External feedback clock compensation time	—	—	—	10	ns
$t_{DYCONFIGCLK}$	Dynamic configuration clock for `mgmt_clk` and `scanclk`	—	—	—	100	MHz
t_{LOCK}	Time required to lock from end-of-device configuration or deassertion of `areset`	—	—	—	1	ms
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	—	1	ms
f_{CLBW}	PLL closed-loop bandwidth	Low	—	0.3	—	MHz
		Medium	—	1.5	—	MHz
		High[64]	—	4	—	MHz
t_{PLL_PSERR}	Accuracy of PLL phase shift	—	—	—	±50	ps
t_{ARESET}	Minimum pulse width on the `areset` signal	—	10	—	—	ns
t_{INCCJ}[65][66]	Input clock cycle-to-cycle jitter	$F_{REF} \geq 100$ MHz	—	—	0.15	UI (p-p)
		$F_{REF} < 100$ MHz	—	—	±750	ps (p-p)

(64) High bandwidth PLL settings are not supported in external feedback mode.
(65) A high input jitter directly affects the PLL output jitter. To have low PLL output clock jitter, you must provide a clean clock source with jitter < 120 ps.
(66) F_{REF} is f_{IN}/N, specification applies when $N = 1$.

DSP Block Performance Specifications

Table 1-37: DSP Block Performance Specifications for Arria V Devices

Mode		Performance			Unit
		–I3, –C4	–I5, –C5	–C6	
Modes using One DSP Block	Independent 9 × 9 multiplication	370	310	220	MHz
	Independent 18 × 19 multiplication	370	310	220	MHz
	Independent 18 × 25 multiplication	370	310	220	MHz
	Independent 20 × 24 multiplication	370	310	220	MHz
	Independent 27 × 27 multiplication	310	250	200	MHz
	Two 18 × 19 multiplier adder mode	370	310	220	MHz
	18 × 18 multiplier added summed with 36-bit input	370	310	220	MHz
Modes using Two DSP Blocks	Complex 18 × 19 multiplication	370	310	220	MHz

Memory Block Performance Specifications

To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL and set to 50% output duty cycle. Use the Quartus Prime software to report timing for the memory block clocking schemes.

When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in f_{MAX}.

Memory Output Clock Jitter Specifications

Table 1-45: Memory Output Clock Jitter Specifications for Arria V Devices

The memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2/DDR3 SDRAM standard.

The memory output clock jitter is applicable when an input jitter of 30 ps (p-p) is applied with bit error rate (BER) 10^{-12}, equivalent to 14 sigma.

Altera recommends using the UniPHY intellectual property (IP) with PHYCLK connections for better jitter performance.

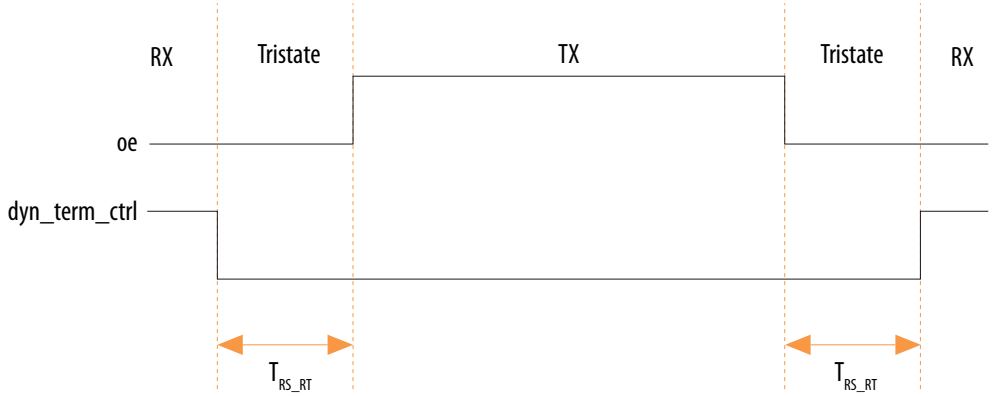
Parameter	Clock Network	Symbol	–I3, –C4		–I5, –C5		–C6		Unit
			Min	Max	Min	Max	Min	Max	
Clock period jitter	PHYCLK	$t_{JIT(per)}$	–41	41	–50	50	–55	55	ps
Cycle-to-cycle period jitter	PHYCLK	$t_{JIT(cc)}$	63		90		94		ps

OCT Calibration Block Specifications

Table 1-46: OCT Calibration Block Specifications for Arria V Devices

Symbol	Description	Min	Typ	Max	Unit
OCTUSRCLK	Clock required by OCT calibration blocks	—	—	20	MHz
T_{OCTCAL}	Number of OCTUSRCLK clock cycles required for R_S OCT/R_T OCT calibration	—	1000	—	Cycles
$T_{OCTSHIFT}$	Number of OCTUSRCLK clock cycles required for OCT code to shift out	—	32	—	Cycles
T_{RS_RT}	Time required between the dyn_term_ctrl and oe signal transitions in a bidirectional I/O buffer to dynamically switch between R_S OCT and R_T OCT	—	2.5	—	ns

Figure 1-7: Timing Diagram for oe and dyn_term_ctrl Signals



Duty Cycle Distortion (DCD) Specifications

Table 1-47: Worst-Case DCD on Arria V I/O Pins

The output DCD cycle only applies to the I/O buffer. It does not cover the system DCD.

Symbol	–I3, –C4		–C5, –I5		–C6		Unit
	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	%

HPS Specifications

This section provides HPS specifications and timing for Arria V devices.

For HPS reset, the minimum reset pulse widths for the HPS cold and warm reset signals (HPS_nRST and HPS_nPOR) are six clock cycles of HPS_CLK1.

HPS Clock Performance

Table 1-48: HPS Clock Performance for Arria V Devices

Symbol/Description	–I3	–C4	–C5, –I5	–C6	Unit
mpu_base_clk (microprocessor unit clock)	1050	925	800	700	MHz
main_base_clk (L3/L4 interconnect clock)	400	400	400	350	MHz
h2f_user0_clk	100	100	100	100	MHz
h2f_user1_clk	100	100	100	100	MHz
h2f_user2_clk	200	200	200	160	MHz

HPS PLL Specifications

HPS PLL VCO Frequency Range

Table 1-49: HPS PLL VCO Frequency Range for Arria V Devices

Description	Speed Grade	Minimum	Maximum	Unit
VCO range	–C5, –I5, –C6	320	1,600	MHz
	–C4	320	1,850	MHz
	–I3	320	2,100	MHz

HPS PLL Input Clock Range

The HPS PLL input clock range is 10 – 50 MHz. This clock range applies to both HPS_CLK1 and HPS_CLK2 inputs.

Related Information

Clock Select, Booting and Configuration chapter
Provides more information about the clock range for different values of clock select (CSEL).

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CK}[105]	nCONFIG high to first rising edge on DCLK	1506	—	µs
t_{ST2CK}[105]	nSTATUS high to first rising edge of DCLK	2	—	µs
t_{DSU}	DATA[] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA[] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency	—	125	MHz
t_{CD2UM}	CONF_DONE high to user mode[106]	175	437	µs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (T_{init} \times$ CLKUSR period)	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Related Information

PS Configuration Timing

Provides the PS configuration timing waveform.

(105) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

(106) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

Date	Version	Changes

December 2015	2015.12.16	• Updated Quad Serial Peripheral Interface (SPI) Flash Timing Requirements for Arria V Devices table.
		  • Updated F_{clk}, $T_{dutycycle}$, and $T_{dssfrst}$ specifications.
		  • Added T_{qspi_clk}, T_{din_start}, and T_{din_end} specifications.
		  • Removed T_{dinmax} specifications.
		• Updated the minimum specification for T_{clk} to 16.67 ns and removed the maximum specification in SPI Master Timing Requirements for Arria V Devices table.
		• Updated Secure Digital (SD)/MultiMediaCard (MMC) Timing Requirements for Arria V Devices table.
		  • Updated T_{clk} to $T_{sdmmc\_clk\_out}$ symbol.
		  • Updated $T_{sdmmc\_clk\_out}$ and T_{d} specifications.
		  • Added T_{sdmmc_clk}, T_{su}, and T_{h} specifications.
		  • Removed T_{dinmax} specifications.
		• Updated the following diagrams:
		  • Quad SPI Flash Timing Diagram
		  • SD/MMC Timing Diagram
		• Updated configuration .rbf sizes for Arria V devices.
		• Changed instances of *Quartus II* to *Quartus Prime*.

Related Information

- **PowerPlay Early Power Estimator User Guide**
  For more information about the EPE tool.
- **PowerPlay Power Analysis**
  For more information about PowerPlay power analysis.

Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus II PowerPlay Power Analyzer feature.

Note: You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

Related Information

- **PowerPlay Early Power Estimator User Guide**
  For more information about the EPE tool.
- **PowerPlay Power Analysis**
  For more information about PowerPlay power analysis.

I/O Pin Leakage Current

Table 2-8: I/O Pin Leakage Current for Arria V GZ Devices

If $V_O = V_{CCIO}$ to $V_{CCIOMax}$, 100 µA of leakage current per I/O is expected.

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0$ V to $V_{CCIOMAX}$	–30	—	30	µA
I_{OZ}	Tri-stated I/O pin	$V_O = 0$ V to $V_{CCIOMAX}$	–30	—	30	µA

Symbol	Parameter	Min	Typ	Max	Unit
t_{OUTPJ_IO}, (173), (175)	Period Jitter for a clock output on a regular I/O in integer PLL ($f_{OUT} \geq 100$ MHz)	—	—	600	ps (p-p)
	Period Jitter for a clock output on a regular I/O in integer PLL ($f_{OUT} < 100$ MHz)	—	—	60	mUI (p-p)
t_{FOUTPJ_IO} (173), (175), (176)	Period Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} \geq 100$ MHz)	—	—	600	ps (p-p)
	Period Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} < 100$ MHz)	—	—	60	mUI (p-p)
t_{OUTCCJ_IO} (173), (175)	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ($f_{OUT} \geq 100$ MHz)	—	—	600	ps (p-p)
	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ($f_{OUT} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{FOUTCCJ\_IO}$ (173), (175), (176)	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} \geq 100$ MHz)	—	—	600	ps (p-p)
	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{CASC\_OUTPJ\_DC}$ (173), (177)	Period Jitter for a dedicated clock output in cascaded PLLs ($f_{OUT} \geq 100$ MHz)	—	—	175	ps (p-p)
	Period Jitter for a dedicated clock output in cascaded PLLS ($f_{OUT} < 100$ MHz)	—	—	17.5	mUI (p-p)
dK_{BIT}	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits

(175) The external memory interface clock output jitter specifications use a different measurement method, which is available in the "Memory Output Clock Jitter Specification for Arria V GZ Devices" table.

(176) This specification only covered fractional PLL for low bandwidth. The f_{VCO} for fractional value range 0.05–0.95 must be ≥ 1000 MHz.

(177) The cascaded PLL specification is only applicable with the following condition:
a. Upstream PLL: 0.59Mhz ≤ Upstream PLL BW < 1 MHz
b. Downstream PLL: Downstream PLL BW > 2 MHz

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
f_{HSCLK_in} (input clock frequency) True Differential I/O Standards (179)	Clock boost factor W = 1 to 40 (180)	5	—	625	5	—	525	MHz
f_{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 (180)	5	—	625	5	—	525	MHz
f_{HSCLK_in} (input clock frequency) Single Ended I/O Standards	Clock boost factor W = 1 to 40 (180)	5	—	420	5	—	420	MHz
f_{HSCLK_OUT} (output clock frequency)	—	5	—	625 (181)	5	—	525 (181)	MHz

Transmitter High-Speed I/O Specifications

Table 2-40: Transmitter High-Speed I/O Specifications for Arria V GZ Devices

When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.

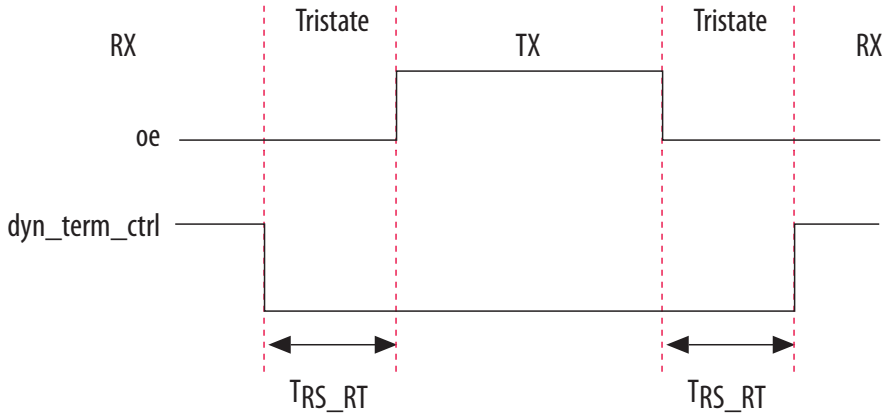
(179) This only applies to DPA and soft-CDR modes.
(180) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.
(181) This is achieved by using the LVDS clock network.

OCT Calibration Block Specifications

Table 2-51: OCT Calibration Block Specifications for Arria V GZ Devices

Symbol	Description	Min	Typ	Max	Unit
OCTUSRCLK	Clock required by the OCT calibration blocks	—	—	20	MHz
T_{OCTCAL}	Number of OCTUSRCLK clock cycles required for OCT R_S/R_T calibration	—	1000	—	Cycles
$T_{OCTSHIFT}$	Number of OCTUSRCLK clock cycles required for the OCT code to shift out	—	32	—	Cycles
T_{RS_RT}	Time required between the `dyn_term_ctrl` and `oe` signal transitions in a bidirectional I/O buffer to dynamically switch between OCT R_S and R_T (See the figure below.)	—	2.5	—	ns

Figure 2-6: Timing Diagram for `oe` and `dyn_term_ctrl` Signals



Date	Version	Changes

June 2016	2016.06.20	• Changed column heading from "Value" to "Maximum" in the "Pin Capacitance for Arria V GZ Devices" table.
		• Changed the minimum supported data rate range values from "1000" to "2000" in the "ATX PLL Specifications for Arria V GZ Devices" table.
		• Added the supported data rates for the following output standards using true LVDS output buffer types in the "High-Speed Clock Specifications for Arria V GZ Devices" table:
		  • True RSDS output standard: data rates of up to 230 Mbps
		  • True mini-LVDS output standard: data rates of up to 340 Mbps

December 2015	2015.12.16	• Removed the CDR ppm tolerance specification from the "Receiver Specifications for Arria V GZ Devices" table. • Removed transmitter rise and fall time specifications from the "Transmitter Specifications for Arria V GZ Devices" table. • Changed the .rbf sizes in the "Uncompressed .rbf Sizes for Arria V GZ Devices" table. • Added a footnote to the "Transmitter High-Speed I/O Specifications for Arria V GZ Devices" table.
June 2015	2015.06.16	• Changed the conditions for the reference clock rise and fall time and added a note to the condition in the "Reference Clock Specifications for Arria V GZ Devices" table. • Added a note to the "Minimum differential eye opening at receiver serial input pins" specification in the "Receiver Specifications for Arria V GZ Devices" table.
January 2015	2015.01.30	• Added 240-Ω to the "OCT Calibration Accuracy Specifications for Arria V GZ Devices" table. • Changed the CDR PPM tolerance spec in the "Receiver Specifications for Arria V GZ Devices" table. • Added additional max data rate for fPLL in the "Fractional PLL Specifications for Arria V GZ Devices" table.

Date	Version	Changes
July 2014	3.8	• Updated Table 21. • Updated Table 22 V_{OCM} (DC Coupled) condition. • Updated the DCLK note to Figure 6, Figure 7, and Figure 9. • Added note to Table 5 and Table 6. • Added the DCLK specification to Table 50. • Added note to Table 51. • Updated the list of parameters in Table 53.
February 2014	3.7	Updated Table 28.
December 2013	3.6	• Updated Table 2, Table 13, Table 18, Table 19, Table 22, Table 30, Table 33, Table 37, Table 38, Table 45, Table 46, Table 47, Table 56, Table 49. • Updated "PLL Specifications".
August 2013	3.5	Updated Table 28.
August 2013	3.4	• Removed Preliminary tags for Table 2, Table 4, Table 5, Table 14, Table 27, Table 28, Table 29, Table 31, Table 32, Table 43, Table 45, Table 46, Table 47, Table 48, Table 49, Table 50, and Table 54. • Updated Table 2 and Table 28.
June 2013	3.3	Updated Table 23, Table 28, Table 51, and Table 55.
May 2013	3.2	• Added Table 23. • Updated Table 5, Table 22, Table 26, and Table 57. • Updated Figure 6, Figure 7, Figure 8, and Figure 9.
March 2013	3.1	• Updated Table 2, Table 6, Table 7, Table 8, Table 19, Table 22, Table 26, Table 29, Table 52. • Updated "Maximum Allowed Overshoot and Undershoot Voltage".
December 2012	3.0	Initial release.